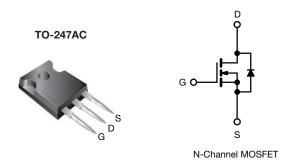


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Vishay Siliconix

EF Series Power MOSFET With Fast Body Diode



PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	850				
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 \text{ V}$	0.305			
Q _g max. (nC)	54				
Q _{gs} (nC)	7				
Q _{gd} (nC)	15				
Configuration	Single				

FEATURES

- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (C_{o(er)})
- Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	TO-247AC
Lead (Pb)-free and halogen-free	SIHG15N80AEF-GE3

ABSOLUTE MAXIMUM RATINGS ($T_C = 25 \degree C$, unless otherwise noted)								
PARAMETER			SYMBOL	LIMIT	UNIT			
Drain-source voltage			V _{DS}	800	v			
Gate-source voltage			V _{GS}	± 30	V			
Continuous drain current ($T_J = 150 \text{ °C}$)	V at 10 V	T _C = 25 °C T _C = 100 °C	1	13				
	VGS AL TU V	T _C = 100 °C		8	А			
Pulsed drain current ^a			I _{DM}	28	1			
Linear derating factor				1.25	W/°C			
Single pulse avalanche energy ^b			E _{AS}	28	mJ			
Maximum power dissipation			PD	156	W			
Operating junction and storage temperature ran	ige		T _J , T _{stg}	-55 to +150	°C			
Drain-source voltage slope		T _J = 125 °C	100					
Reverse diode dv/dt ^d		dv/dt	15	V/ns				
Soldering recommendations (peak temperature)) c	For 10 s		260	°C			

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature

b. V_{DD} = 140 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 1.4 A

c. 1.6 mm from case

d. $I_{SD} \leq I_D$, di/dt = 100 A/µs, starting T_J = 25 °C

COMPLIANT

HALOGEN

FREE



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PARAMETER	SYMBOL	TYP.		MAX.		UNIT		
Maximum junction-to-ambient	R _{thJA}	-	- 40					
Maximum junction-to-case (drain)	R _{thJC}	- 0.8				°C/W		
SPECIFICATIONS (T _J = 25 $^{\circ}$ C,	unless otherw	ise noted)						
PARAMETER	SYMBOL		T CONDITIO	NS	MIN.	TYP.	MAX.	UNI
Static					•	•		
Drain-source breakdown voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 250) μA	800	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D	= 1 mA	-	0.7	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250) μΑ	2	-	4	V
Cata agurag lagkaga	1	,	$V_{GS} = \pm 20 V$ $V_{GS} = \pm 30 V$		-	-	± 100	nA
Gate-source leakage	IGSS				-	-	± 1	μA
Zero gate voltage drain current	L	V _{DS} =	= 640 V, V _{GS} =	0 V	-	-	1	μA
	I _{DSS}	V _{DS} = 640 V	V _{DS} = 640 V, V _{GS} = 0 V, T _J = 125 °C			-	2	mA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D =	6.5 A	-	0.305	0.350	Ω
Forward transconductance ^a	9 _{fs}	V _{DS}	= 10 V, I _D = 6.	5 A	-	7.0	-	S
Dynamic						-		
Input capacitance	C _{iss}	$V_{GS} = 0 V,$ $V_{DS} = 100 V,$ $f = 1 MHz$ $V_{DS} = 0 V \text{ to } 480 V, V_{GS} = 0 V$		-	1128	-	pF	
Output capacitance	C _{oss}			-	41	-		
Reverse transfer capacitance	C _{rss}			-	5	-		
Effective output capacitance, energy related	C _{o(er)}			-	34	-		
Effective output capacitance, time related	C _{o(tr)}			-	209	-		
Total gate charge	Qg			-	36	54		
Gate-source charge	Q _{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 6.5 \text{ A}, V_{DS} = 640 \text{ V}$		-	7	-	nC
Gate-drain charge	Q _{gd}				-	15	-	1
Turn-on delay time	t _{d(on)}				-	14	28	
Rise time	t _r	V _{DD} =	$\label{eq:VDD} \begin{array}{l} V_{DD} = 640 \; V, I_{D} = 6.5 \; A, \\ V_{GS} = 10 \; V, R_{g} = 9.1 \; \Omega \end{array}$		-	14	28	ns
Turn-off delay time	t _{d(off)}	V _{GS} =			-	18	36	
Fall time	t _f	-		-	43	86		
Gate input resistance	R _g	f = 1 MHz, open drain		0.2	0.5	1.1	Ω	
Drain-Source Body Diode Characteris	tics							
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	13	A	
Pulsed diode forward current	I _{SM}			-	-	28		
Diode forward voltage	V _{SD}	$T_{J} = 25 \text{ °C}, I_{S} = 6.5 \text{ A}, V_{GS} = 0 \text{ V}$		-	-	1.2	V	
Reverse recovery time	t _{rr}	$T_{\rm J} = 25 ^{\circ}\text{C}, I_{\rm F} = I_{\rm S} = 6.5 \text{A}, \\ \text{di/dt} = 100 \text{A/}\mu\text{s}, \text{V}_{\rm R} = 25 \text{V}$		-	104	208	ns	
Reverse recovery charge	Q _{rr}			-	0.4	0.8	μC	
Reverse recovery current	I _{RRM}			-	8	-	A	



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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

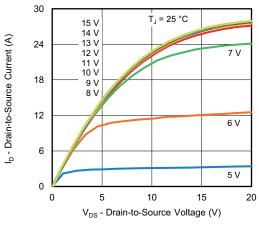


Fig. 1 - Typical Output Characteristics

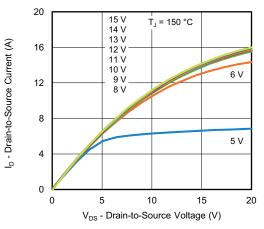


Fig. 2 - Typical Output Characteristics

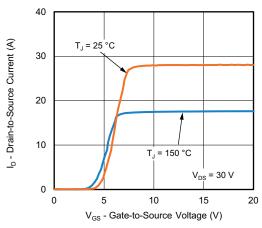


Fig. 3 - Typical Transfer Characteristics

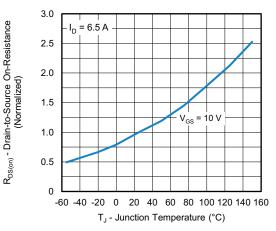


Fig. 4 - Normalized On-Resistance vs. Temperature

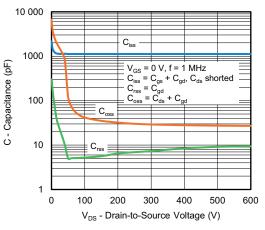


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

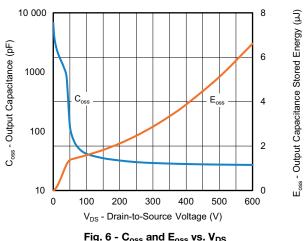


Fig. 6 - Coss and Eoss vs. VDS

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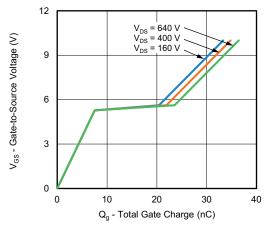


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

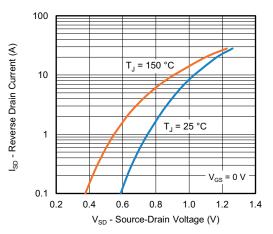


Fig. 8 - Typical Source-Drain Diode Forward Voltage

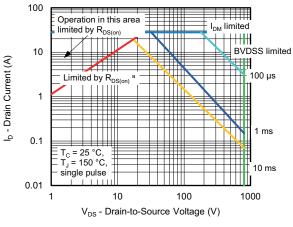


Fig. 9 - Maximum Safe Operating Area

Note

a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

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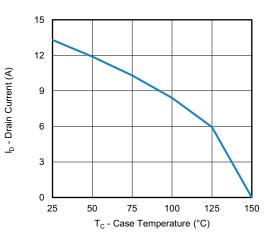


Fig. 10 - Maximum Drain Current vs. Case Temperature

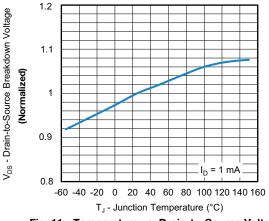


Fig. 11 - Temperature vs. Drain-to-Source Voltage



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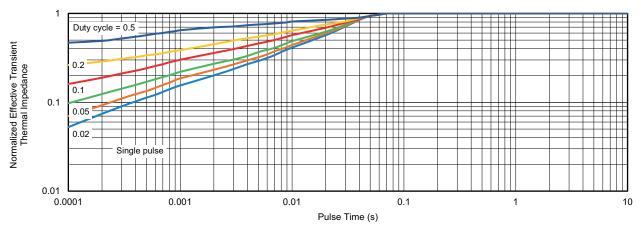


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

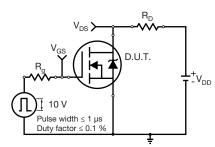


Fig. 13 - Switching Time Test Circuit

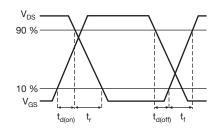


Fig. 14 - Switching Time Waveforms

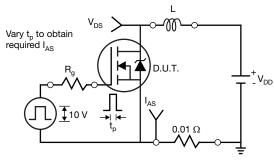


Fig. 15 - Unclamped Inductive Test Circuit

Fig. 16 - Unclamped Inductive Waveforms

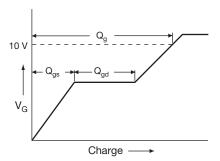


Fig. 17 - Basic Gate Charge Waveform

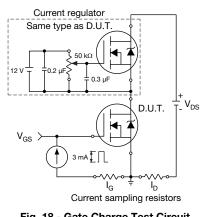


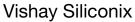
Fig. 18 - Gate Charge Test Circuit

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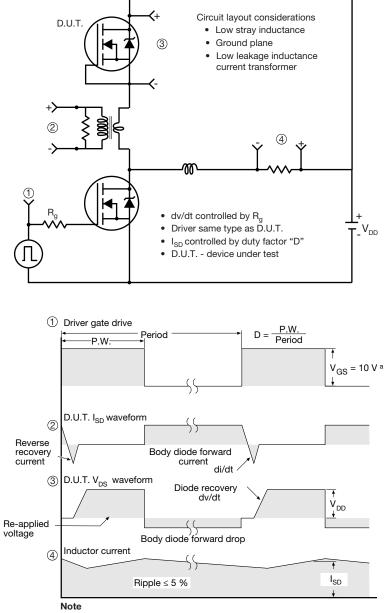
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Peak Diode Recovery dv/dt Test Circuit



a. $V_{GS} = 5$ V for logic level devices

Fig. 19 - For N-Channel

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